Model 6200

Automatic Die Attach System

Performs **MCM, Flip Chip, Eutectic, Silver Glass, Ag Sintering etc** die attach applications.

Small footprint, **Table-Top** configuration.

Versatile and **User Friendly** machine using the same advanced software of Model 6400 running under Windows® on a PC platform.

Fully automatic and Semi-automatic process allowing highest flexibility and easy operation.

Very High Accuracy closed loop servo systems control the main motion axes.

High resolution **Digital Vision** and **Image Processing** system.

Time-Pressure or **Volumetric Dispenser** for applying complex shapes of adhesive.

Double Dispenser for two different adhesives.

Stamping (Pin Transfer) 75 µm adhesive dots.

Die Presentation:

- Up to 10 Waffle/Gel packs 2”.
- Up to 8 Tape & Reel feeders.
- Future option: one 8” Wafer, Manual Indexing.
- Combinations of the above.

Unique one-pass, wet **Die Stacking** capability with **BLT control** of the dice.

Capability to handle **MEMS** devices.

Experience with very large **Imaging Devices**.

Flip Chip process including chip flipping, bump fluxing and final alignment over a high resolution Up Looking Camera.

Eutectic MCM processes based on heated substrates with gas cover and heated pickup tools with provision of forming gas.

Ultrasonic bond head available for Gold to Gold Interconnection.

Specification Highlights

Work Area: up to 6” x 6”.

Die size range: 0.006” to over 2”

Die Material: GaAs, Si, Glass, etc.

Substrates: Lead Frames, Ceramic, Silicon Wafers, PCB’s, Metal, TO cans, etc.

Pickup/Bond Force: 40 to 9,000 grams.

Placement Accuracy: better than ±3 µm - application dependent.

Throughput: up to 700 CPH - application dependent.

Size: 0.97 x 0.85 x 0.65 meter.

Weight: under 200 Kg.

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